



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SC-75					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	280	140 000	200 °C + N2	0	0
HAST	1120	110 200	130 °C, 85 % RH	0	0
Pressure Pot	1302	165 992	121°, 15 PSIG	0	0
Solder DUNK	95	285	260 °C, 10 s	0	0
Solderability	45	360	883 M2003	0	0
Temp. Cycle	2202	1 441 000	-55 °C to 150 °C	0	0